



Product Change Notification: CBOL-19HCTE752

Date:

26-Aug-2026

Product Category:

Power Management - System Supervisors/Voltage Detectors

Notification Subject:

CCB 8470 Initial Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material, 84-3J as new die attach material and G700LTD as new mold compound material for selected TC1270A, TC1271A and TC1270AN device families available in 4L SOT-143 package.

Affected CPNs:

[CBOL-19HCTE752_Affected_CPN_08262026.pdf](#)

[CBOL-19HCTE752_Affected_CPN_08262026.csv](#)

PCN Status: Initial Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material, 84-3J as new die attach material and G700LTD as new mold compound material for selected TC1270A, TC1271A and TC1270AN device families available in 4L SOT-143 package.

Pre and Post Summary Changes:

	Pre Change	Post Change	Change (Yes/No)
Assembly Site	Stars Microelectronics (Thailand) Public Company Limited (STAR)	Stars Microelectronics (Thailand) Public Company Limited (STAR)	No
Wire Material	Au	CuPdAu	Yes

Die Attach Material	8900NC (PFAS)	84-3J (PFAS Free)	Yes
Molding Compound Material	G600	G700LTD	Yes
Lead-Frame Material	A194	A194	No

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve manufacturability by qualifying palladium coated copper with gold flash (CuPdAu) as a new bond wire material, 84-3J as new die attach material and G700LTD as new mold compound material.

Change Implementation Status: In Progress

Estimated Qualification Completion Date: January 2027

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Timetable Summary:

	August 2026					>	January 2027			
Work Week	32	33	34	35	36		01	02	03	04
Initial PCN Issue Date				X						
Qual Report Availability										X
Final PCN Issue Date										X

Method to Identify Change: Traceability Code

Qualification Plan: Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History: August 26, 2026: Issued initial notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PFAS Elimination and Die Attach_Explanation.pdf
PCN_CBOL-19HCTE752_Qual Plan.pdf

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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